

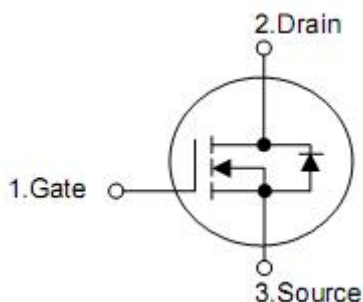
## 1. Features

KNX3403C is an N-channel enhancement mode power Mosfet field effect transistor which is produced using KIA's LVMosfet technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance. This device is widely used in UPS, Power Management for Inverter Systems.

## 2. Features

- 80A, 30V,  $R_{DS(on)}$ ( typ. )= 5.0m $\Omega$ @ $V_{GS} = 10\text{ V}$
- Low gate charge
- Low Crss
- Fast switching
- Improved dv/dt capability

## 3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source

## 4. Ordering Information

Part Number	Package	Brand
KND3403C	TO-252	KIA

## 5. Absolute maximum ratings

(T<sub>C</sub> = 25°C , unless otherwise noted)

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain-Source Voltage	30	V
I <sub>D</sub>	Drain Current -Continuous (T <sub>C</sub> = 25 °C) -Continuous (T <sub>C</sub> = 100 °C)	80	A
		57	A
I <sub>DM</sub>	Drain Current -Pulsed	320	A
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 1)	110.25	mJ
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25 °C) -Derate above 25 °C	65	W
		0.47	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C

## 6. Thermal Characteristics

Symbol	Parameter	Value	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	0.52	°C /W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	62	°C /W

## 7. Electrical characteristics

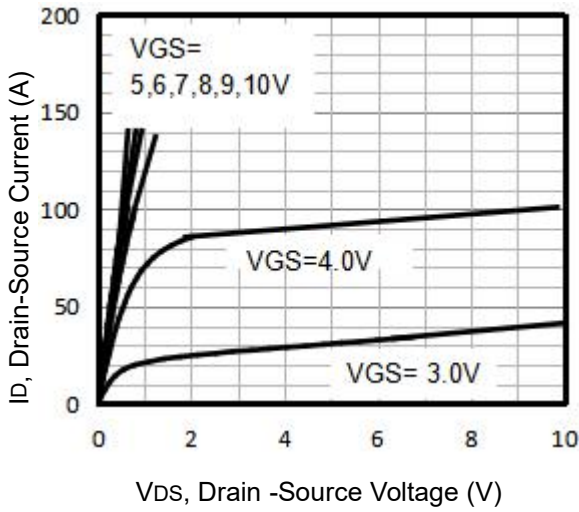
(T<sub>C</sub> = 25°C , unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
B <sub>VDS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 uA	30	--	--	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	--	--	1	uA
I <sub>GSS</sub>	Gate- Source Leakage Current	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	--	--	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 uA	0.8	1.3	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A	--	5.0	6.2	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10 A	--	7.5	9.0	mΩ
R <sub>G</sub>	Gate Resistance	f = 1.0 MHz, V <sub>DS</sub> = 0 V, V <sub>GS</sub> = 0 V,	--	1.5	--	Ω
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz	--	2500	--	pF
C <sub>oss</sub>	Output Capacitance		--	1250	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	1100	--	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 15 V, V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 1 A, R <sub>G</sub> = 3Ω (Note 2,3)	--	7	--	ns
t <sub>r</sub>	Turn-On Rise Time		--	3.6	--	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		--	36.8	--	ns
t <sub>f</sub>	Turn-Off Fall Time		--	22.5	--	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 25V, I <sub>D</sub> = 14A , V <sub>GS</sub> = 10V (Note 2,3)	--	38.9	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	4.48	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	10.78	--	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Continuous Source Current	Integral Reverse P-N Junction Diode in the MOSFET	--	--	80	A
I <sub>SM</sub>	Pulsed Source Current		--	--	320	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 20 A	--	--	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 20 A, dI <sub>F</sub> / dt = 100 A/us (Note 2)	--	12.8	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	3.3	--	nC

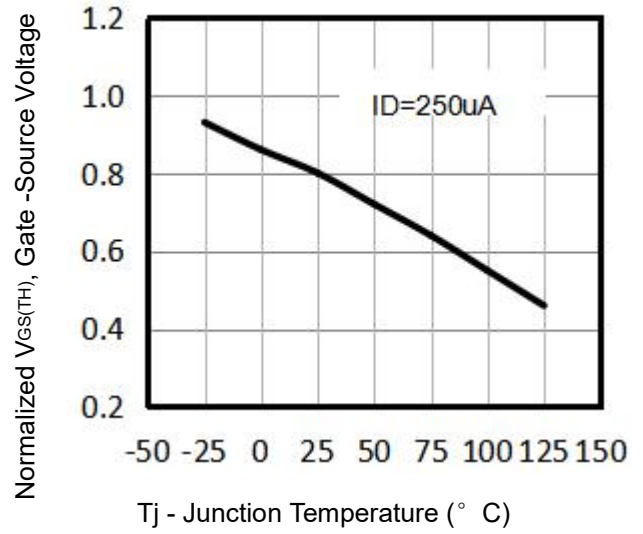
Notes:

- L = 0.5mH, V<sub>DD</sub> = 25V, V<sub>GS</sub> = 10V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C
- Pulse Test : Pulse width ≤ 300us, Duty cycle ≤ 2%
- Essentially independent of operating temperature

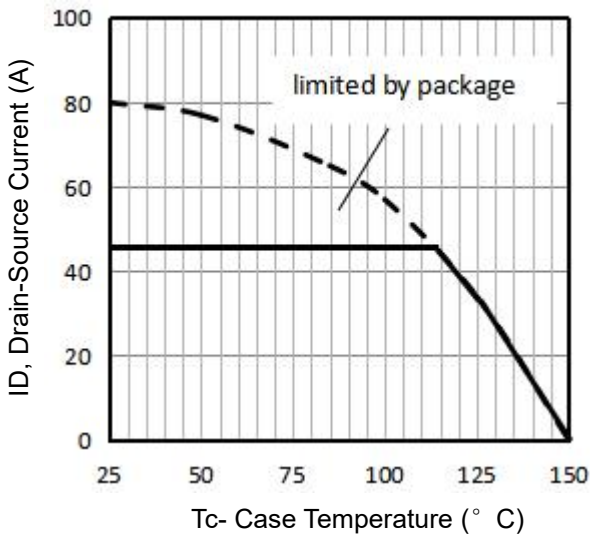
**8. Typical Characteristics**



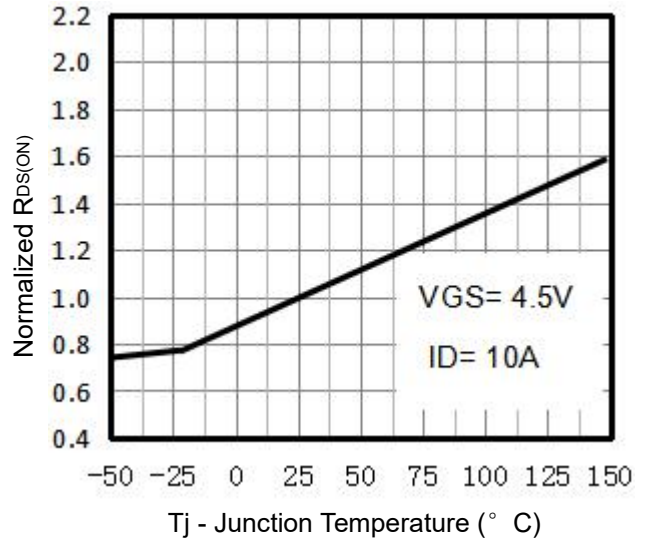
**Fig1.** Typical Output Characteristics



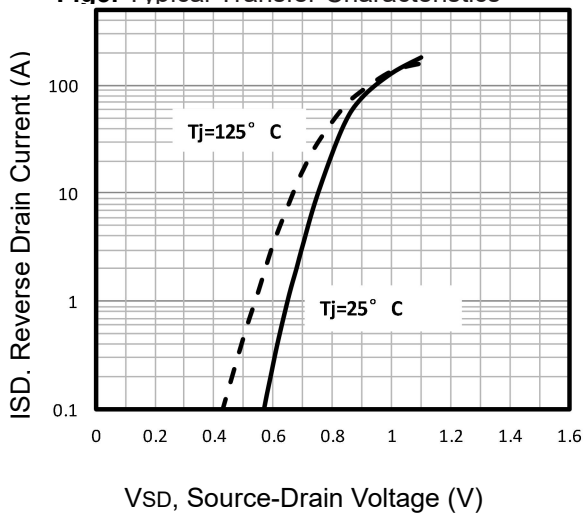
**Fig2.** Normalized Threshold Voltage Vs. Temperature



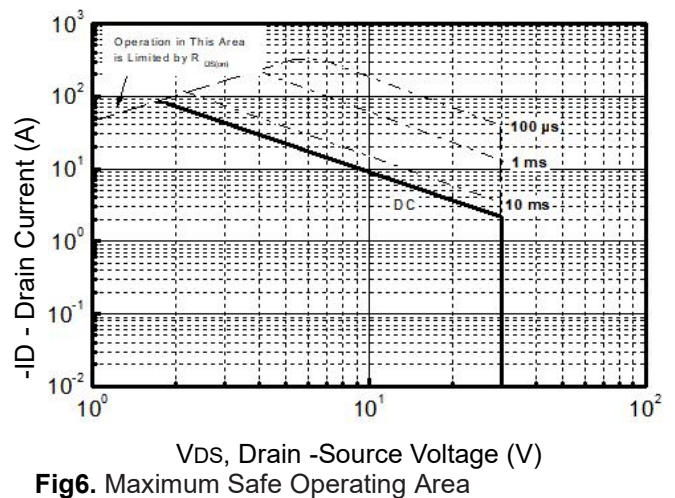
**Fig3.** Typical Transfer Characteristics



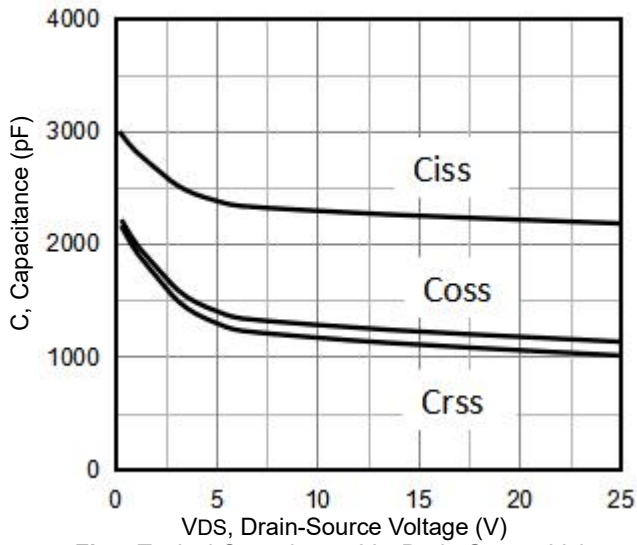
**Fig4.** Normalized Threshold Voltage Vs. Temperature



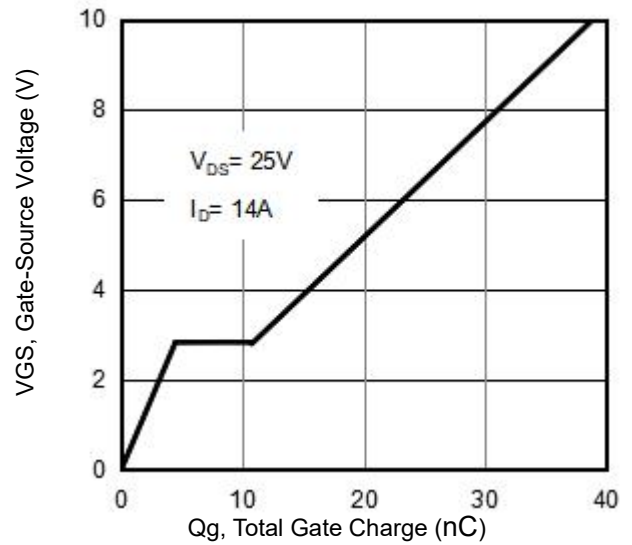
**Fig5.** Typical Source-Drain Diode Forward



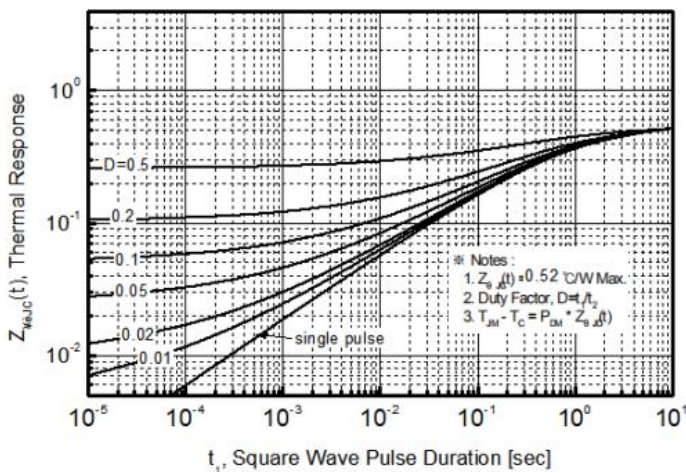
**Fig6.** Maximum Safe Operating Area



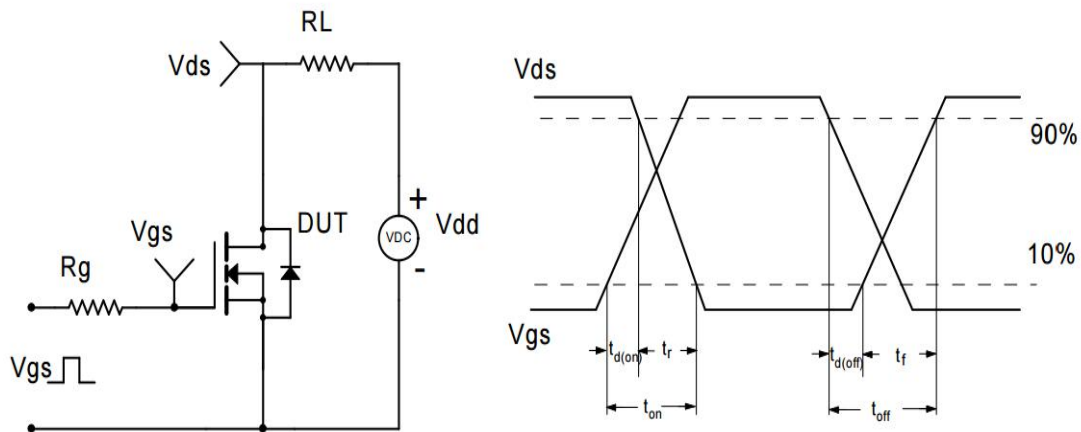
**Fig7.** Typical Capacitance Vs. Drain-Source Voltage



**Fig8.** Typical Gate Charge Vs. Gate-Source Voltage



**Fig9.** Transient Thermal Response Curve



**Fig10.** Switching Time Test Circuit and waveforms